

03-22-2004



FORM 1595

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7/22/03

To the Honorable Commissioner of Patents and Trademarks. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
**Yasuaki MASHIKO
Hideshi SEKIMORI
Naotomi TAKAHASHI**
Additional name(s) of conveying party(ies) attached? Yes No

2. Name and address of receiving party(ies):
NAME:
Mitsui Mining & Smelting Co., Ltd.
ADDRESS:

3. Name of Conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other
Execution/Effective Date: **May 15, 2003** all

**11-1, Osaki 1-chome,
Shinagawa-ku, Tokyo 141-8584, Japan**
Additional name(s) & addresses(es) attached?
 Yes No


4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: _____
A. Patent Application No.(s)
10/466,886
B. Patent No.(s)
Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: **MURRAY, Robert B.**
Internal Address: **Rothwell, Figg, Ernst & Manbeck
Suite 800**
Street Address: **1425 K St., N.W.**
City: **Washington,**
State: **D.C.** Zip: **20005**
Telephone No.: **202/783-6040**
Facsimile No.: **202/783-6031**
Attorney Docket No.: **2922-0460**

6. Total number of applications and patents involved: 1
7. Total fee (37 CFR 3.41): \$ 40.00
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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.
Robert B. Murray, Registration No. 22,980
Name of Person Signing  **7/22/03**
Date

Total number of pages including cover sheet, attachments and documents: 2

FP-02287 / 1150739-OP (P44)

譲渡証

Attorney Docket Number:

Rothwell, Figg, Ernst & Manbeck, P.C

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, I/We Yasuaki Mashiko, a citizen of JAPAN

residing at c/o Mitsui Mining & Smelting Co., Ltd. Corporate R&D Center, 1333-2 Haraichi, Ageo-shi, Saitama 362-0021, Japan,

Hideshi Sekimori, a citizen of JAPAN

residing at c/o Mitsui Mining & Smelting Co., Ltd. Corporate R&D Center, 1333-2 Haraichi, Ageo-shi, Saitama 362-0021, Japan,

and Naotomi Takahashi, a citizen of JAPAN

residing at c/o Mitsui Mining & Smelting Co., Ltd. Copper Foil Sector Copper Foil Division, 656-2, Kamakurabashi, Ageo-shi, Saitama 362-0013, Japan

ASSIGNOR(S), am/are the inventor(s) of an invention in (insert title) LAMINATE FOR FORMING CAPACITOR LAYER AND METHOD FOR MANUFACTURING THE SAME

for which I/we have executed an application for Letters Patent of the United States,

() of even date herewith;

(Check One) () U.S. Serial Number _____ filed _____;

(X) International Application No. PCT/JP02/09860 filed on September 25, 2002

and

WHEREAS, Mitsui Mining & Smelting Co., Ltd. (Japanese corporation) of 11-1, Osaki 1-chome, Shinagawa-ku, Tokyo 141-8584, JAPAN

ASSIGNEE, is desirous of obtaining the entire right, title and interest in, to and under the said invention and the said application;

NOW, THEREFORE, in consideration of the sum of One Dollar (\$1.00) to me/us in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, I/we, the said ASSIGNOR(S) have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title and interest in, to and under the said invention, and the said application and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reexamination certificates, reissues and extensions thereof, and I/we hereby authorize and request the Commissioner of Patents of the United States, to issue all Letters Patent for said invention to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I/WE HEREBY covenant that I/we have the full right to convey the entire interest herein assigned, and that I/we have not executed, and will not execute, any agreement in conflict herewith.

AND I/WE HEREBY further covenant and agree that I/we will communicate to said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me/us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention at the expense of the ASSIGNEE.

IN TESTIMONY WHEREOF, I/we hereunto set my/our hand(s) and seal(s) the day and year set opposite my/our signature(s).

Yasuaki Mashiko Yasuaki Mashiko L.S. Date 15/05, 20 03
Hideshi Sekimori Hideshi Sekimori L.S. Date 15/05, 20 03
Naotomi Takahashi Naotomi Takahashi L.S. Date 15/05, 20 03
L.S. Date _____, 20 03

Witness: Yoshiyuki Ohtsuka May 15, 2003
Name Yoshiyuki OHTSUKA Date

Foreign Inventor Sole/Joint Assignment